

PACKAGE: SC70-6 (GREEN)

MATERIALS DECLARATION:

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	Copper (A194)	2.9068	Cu	7440-50-8	97.5	2.8341	44.9395	449395.47
				Fe	7439-89-6	2.35	0.0683	1.0832	10831.58
				Zn	7440-66-6	0.12	0.0035	0.0553	553.10
				P	7723-14-0	0.03	0.0009	0.0138	138.28
2	Die attach material	Ablebond 8006NS	0.0051	Treated silica (5-10)	Proprietary	9	0.0005	0.0073	72.78
				Glycol ethers (10-30)	Proprietary	22	0.0011	0.0178	177.91
				Metal oxide (15-40)	Proprietary	30	0.0015	0.0243	242.60
				Curing agent & hardener (5-10)	Proprietary	9	0.0005	0.0073	72.78
				Epoxy resins (15-40)	Proprietary	30	0.0015	0.0243	242.60
3	Gold Wire	Gold	0.0502	Au	7440-57-5	99.99	0.0502	0.7959	7958.89
4	Tin Plate	Pure Tin	0.2243	Sn	7440-31-5	100	0.2243	3.5561	35561.27
5	Mold Compound	G600	2.8361	Silica Fused (75 - 95)	60676-86-0	86.7	2.4589	38.9896	389895.63
				Epoxy Resin (2 - 8)	Trade secret	6	0.1702	2.6982	26982.40
				Epoxy, Cresol Novolac (1 - 3)	29690-82-2	2	0.0567	0.8994	8994.13
				Phenol Resin (2 - 8)	Trade secret	5	0.1418	2.2485	22485.33
				Carbon Black (0.1 - 0.5)	1333-86-4	0.3	0.0085	0.1349	1349.12
6	Die	Silicon Chip	0.2478				0.2478	3.9292	39292.29
Total unit weight =			6.3066						

REVISION HISTORY

Revision	Date	Description
A	4/9/2015	Initial Release